



## SOT-223



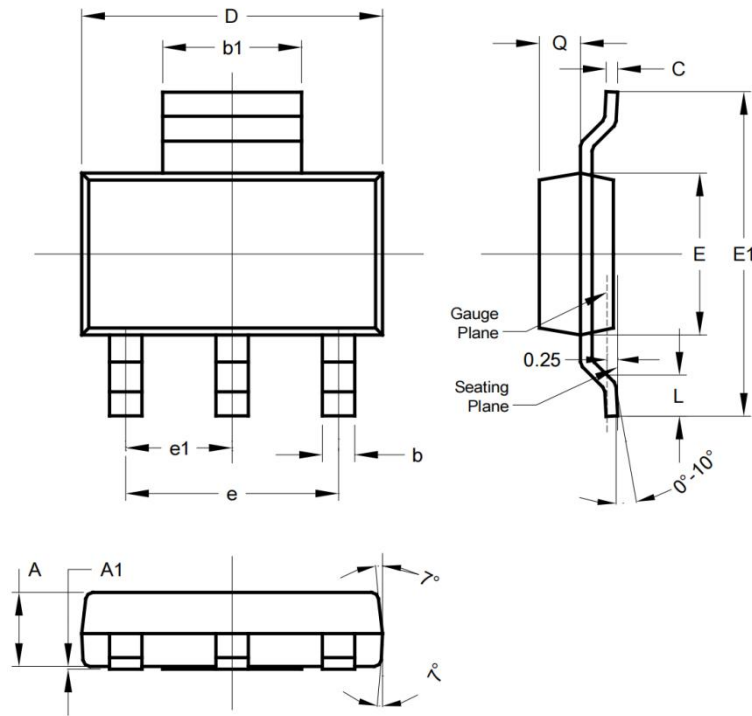
Plastic, surface-mounted package; 4 terminals;  
2.3 mm pitch; 6.5 mm x 3.5 mm x 1.65 mm body  
塑料表面贴装封装；4 引脚；间距 2.3 mm；  
封装本体尺寸 6.5 mm x 3.5 mm x 1.65 mm

### 1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SOT-223
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	2.3mm pitch; 6.5mm × 3.5mm × 1.65mm body 相邻引脚中心距为 2.3mm，封装本体（不含引脚）尺寸为 6.5mm × 3.5mm × 1.65mm
Terminals Compliance 引脚合规	4 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 <sup>③</sup> 4 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.112 grams (Approximate) 约 0.112 克

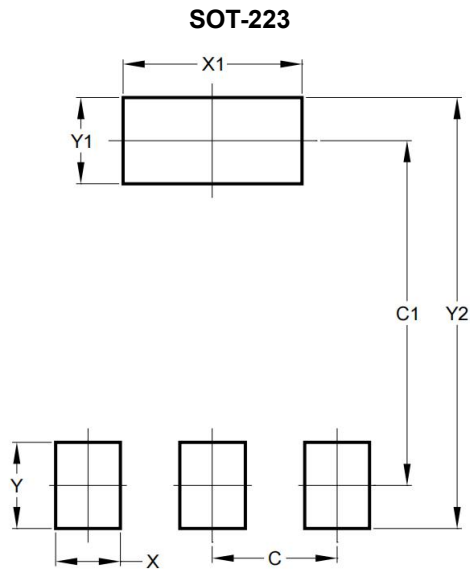
## 2. Package Outline Dimensions 封装外形尺寸

SOT-223



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	1.55	1.65
A1	0.01	0.15
b	0.60	0.80
b1	2.90	3.10
C	0.20	0.30
D	6.45	6.55
E	3.45	3.55
E1	6.90	7.10
e	4.40	4.80
e1	2.20	2.40
L	0.85	1.05
Q	0.84	0.94

### 3. Suggested Pad Layout 推荐焊盘布局



Dimensions 尺寸	Millimeters 毫米
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

Fig. Soldering footprint for SOT-223

图 SOT-223 的引脚焊接

### 4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
13	12	2500

**Note:**

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

**说明:** 上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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